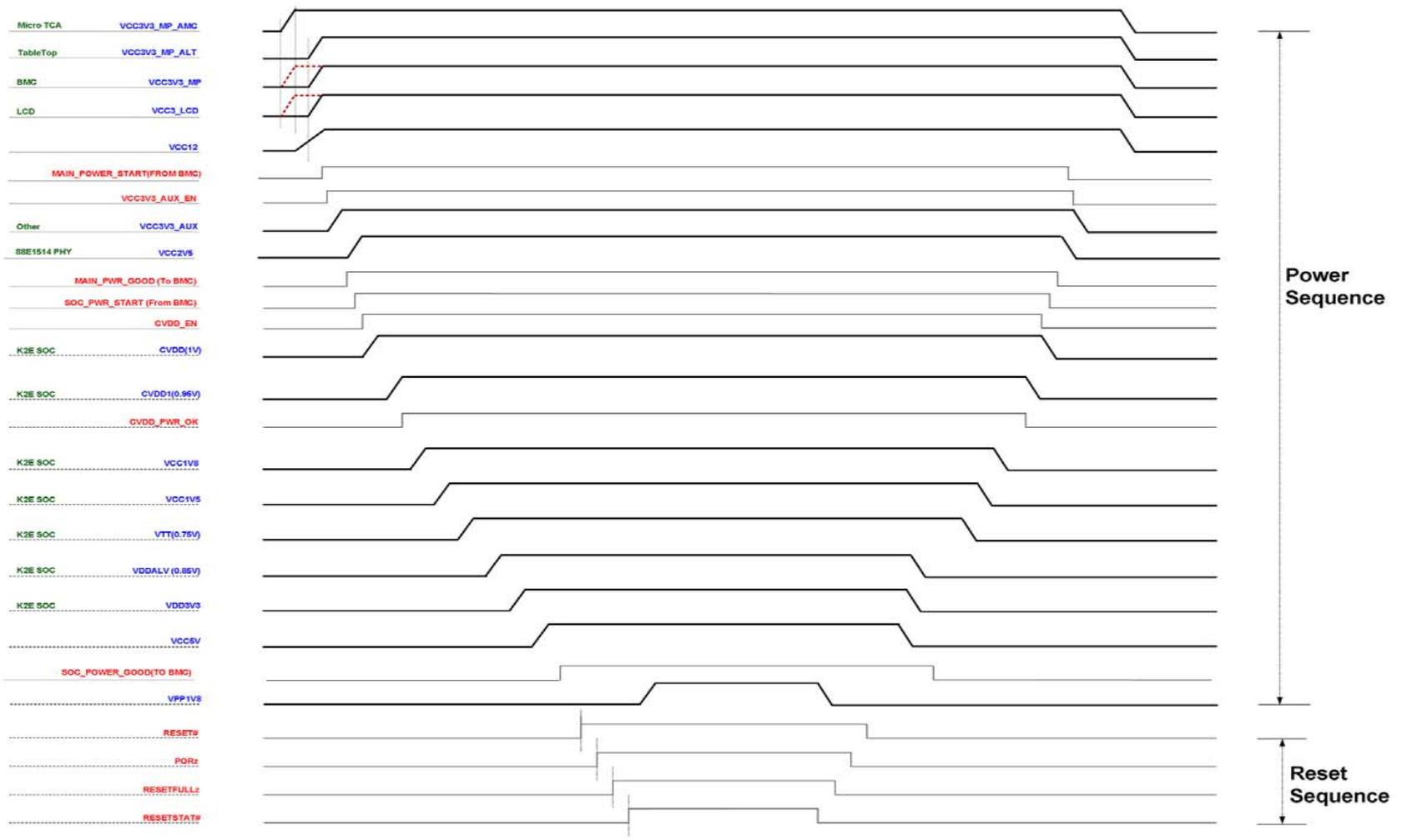
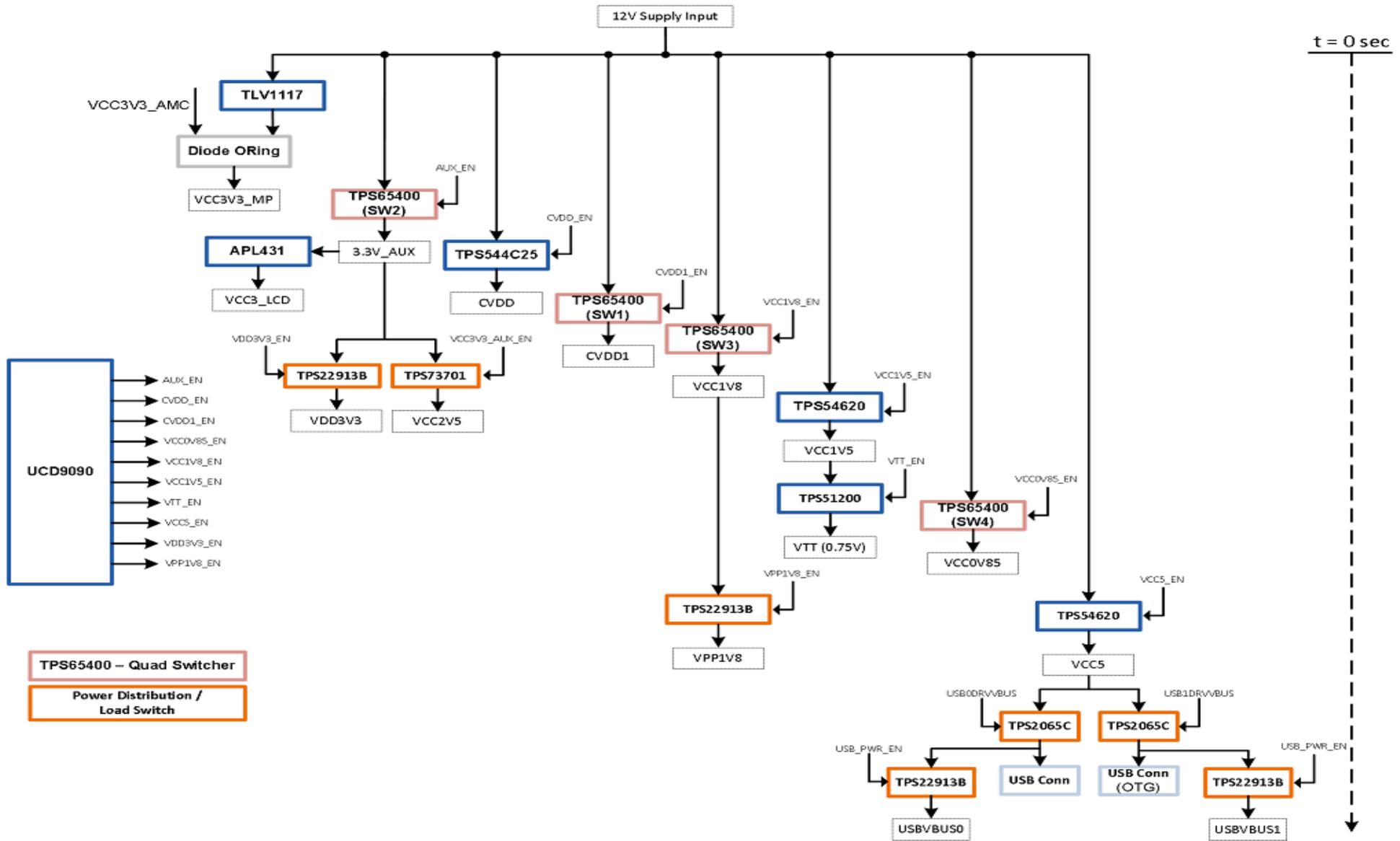


K2E_EVM (EDISON) -- POWER SEQUENCE



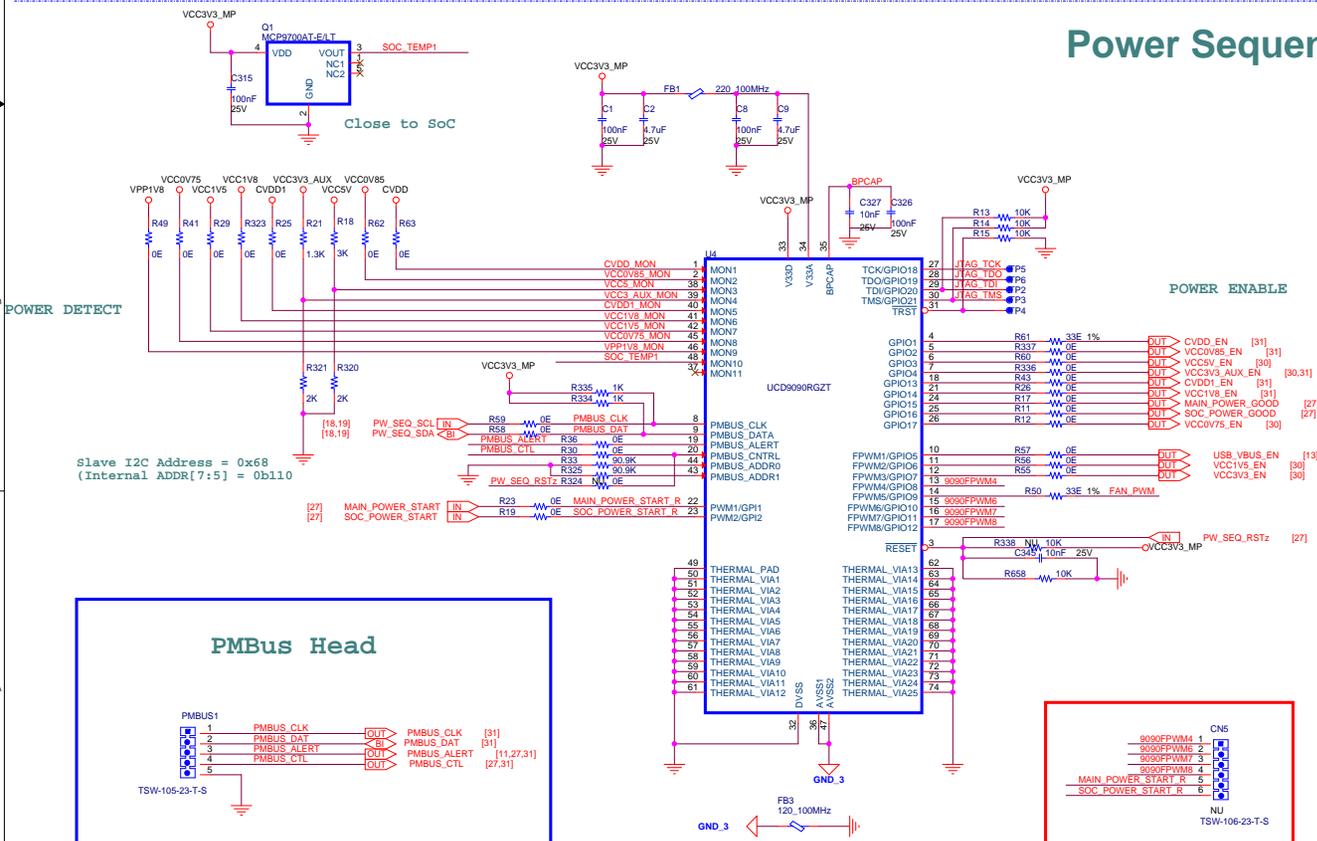
Project K2E EVM		Designed for TI by elfin chips	
Title POWER SEQUENCING		  The Solutions People	
Size C	Document Number 16_00175_01	Rev 1.0	
Date: Wednesday, February 25, 2015		Sheet 6 of 37	

EDISON – Power Tree



Project		K2E EVM		Designed for TI by elfnchips	
Title		POWER DISTRIBUTION			
Size	Document Number			Rev	
C	16_00175_01			1.0	
Date: Wednesday, February 25, 2015				Sheet 7 of 37	

Power Sequencing (UCD9090)



PMbus Address Pins

PMbus Address	PMbus RESISTANCE (K ohm)
OPEN	--
11	200
10	154
9	118
8	90.9
7	69.8
6	53.6
5	41.2
4	31.6
SHORT	--

Project K2E EVM		Designed for TI by elfnchips	
Title MCU_MISC			
Size C	Document Number 16_00175_03	Rev 3.02	
Date: Wednesday, February 25, 2015		Sheet 28 of 37	

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